# **Surface Mount Quad Photodiode**

# **OPR5911**

#### Features:

- Surface mountable
- Closely matched responsivity •
- High temperature operation •
- Common cathode connections





#### Description:

Each OPR5911 device is a four-element photodiode that is enclosed in a compact polyimide chip carrier and designed for a variety of encoder and control applications. The single chip construction ensures excellent matching and very tight dimensional tolerances between active areas. The custom opaque package shields the photodiodes from stray light and can withstand multiple exposures to the most demanding soldering conditions, while the wraparound gold-plated solder pads offer exceptions storage and wetting characteristics.

All cathodes in the OPR5911 are bonded together, which enables the elements to act in unison with limited external circuitry.

See Application Bulletin 237 for handling considerations.

#### Application

olications:	Ordering Information						
Encoder applications Control applications	Part Number	Receiver Type	# of Elements	Responsivity (mA/mW) Min.	Reverse Voltage Min.	Active Area (mm <sup>2</sup> )	Packaging
	OPR5911	Photodiode Array	4	0.45	14	1.61 (each)	Chip Tray



General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

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## **Electrical Specifications**

#### Absolute Maximum Ratings (T<sub>A</sub> = 25° C unless otherwise noted)

Storage and Operating Temperature	-55° C to +125° C
Reverse Breakdown Voltage	14 V / minute
Solder reflow time within 5°C of peak temperature is 20 to 40 seconds $^{(1)}$	250° C

#### Electrical Characteristics (T<sub>A</sub> = 25° C unless otherwise noted)

SYMBOL	PARAMETER	MIN	ТҮР	МАХ	UNITS	TEST CONDITIONS
R	Responsivity	0.45	I	—	A/W	$E_e$ = 10 $\mu$ W, $\lambda$ = 850 nm, V <sub>R</sub> = 0
V <sub>BR</sub>	Reverse Breakdown Voltage	14	-	_	V	I <sub>R</sub> = 100 μA
I <sub>D</sub>	Reverse Dark Current	-	-	30	nA	V <sub>R</sub> = 10 V
CT	Capacitance	-	10	-	pF	V <sub>R</sub> = 10 V
LXW	Active Area (per diode)	—	1.61	-	mm²	(1.27 mm x 1.27 mm)

Notes:

1. Solder time less than 5 seconds at temperature extreme.



#### **Spectral Responsivity**

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# Packaging

### Bare Die/CSP Tray Detail



POCKET	LOCATIONS
М	= 0.592" ±0.005"
M1	= 0.592" ±0.005"
M2	= 0.401" ±0.005"
M3	= 0.401" ±0.005"
Array	=8x8 (64)
POCKET	DETAILS
х	= 0.361" ±0.005" pocket size
Y	= 0.361" ±0.005" pocket size
Z	= 0.100" ±0.005" pocket depth
Α	= 5° ±1/2° pocket draft angle
	No Cross Slots
OVERAL	L TRAY SIZE
Size	= 3.990" ±0.010"
Height	= 0.315" +0.005" -0.005"
Flatness	= 0.020"

#### H44-359-62C02

UNIT OF MEASURE		
English		
C Metric		

Orientation



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